

HeBoFill®
COOL LINE

Cooling effect included

The technology behind foldable mobile phones, tablets, e-mobility is constantly evolving. Today's electronic components achieve maximum performance in the smallest possible installation space. Heat is the main result, which has to be dissipated to increase the components' service life, on the one hand, and to guarantee functional reliability on the other. Here, boron nitride powder is more in demand than ever before. This is because they are considered the ideal filler for increasing thermal conductivity, found, for example, in plastics. The **HeBoFill® COOL LINE** is absolutely pre-destined for these application scenarios. It was developed and refined specifically for this purpose. The thermal conductivity can be increased many times over by adding boron nitrides, while at the same time maintaining the electrical insulating effect. Boron nitride powder's excellent lubricating and anti-friction properties ensure a smooth production process during compounding. Compared to other conventional fillers, system wear is reduced to a minimum with the use of the **HeBoFill® COOL LINE** fillers. Saving costs in your production

	HeBoFill® CL-ADM 020	HeBoFill® CL-SP 009	HeBoFill® CL-SP 015
Colour	White	White	White
Purity (B+N)	> 99.0 %	> 98.0 %	> 99.7 %
Oxygen	< 0.5 %	< 1.0 %	< 0.3 %
Boron Oxide	< 0.1 %	< 0.5 %	< 0.1 %
Carbon	< 0.1 %	< 0.1 %	< 0.1 %
Specific Surface Area (BET)	~ 3 m ² /g	~ 2.7 m ² /g	~ 2.7 m ² /g
Median Grain Size (D₅₀)	20 µm	~ 9 µm	~ 15 µm

-  Particel size
-  Specific surface area
-  Degree of agglomeration
-  Crystallinity
-  Pourability
-  Bulk density
-  Particle size distribution



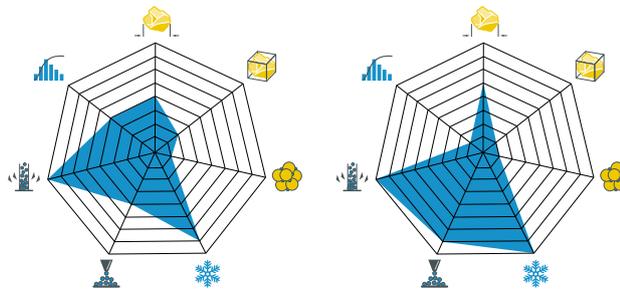
The data quoted in this leaflet are typical for the material. They are intended as a guide only and should not be used in preparing detailed specifications. Actual product data may deviate from the figures given. We reserve the right to alter product data within the scope of technical progress and new developments. Since processing involves factors that are beyond our control, recommendations made in this leaflet should be checked by preliminary trials, especially for third party applications. These recommendations do not absolve the user from the obligation of investigating the possibility of infringement of third parties' rights and, if necessary, from clarifying the situation.

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	HeBoFill® CL-SP 035	HeBoFill® CL-SP 045
Colour	White	White
Purity (B+N)	> 99.0 %	> 98.5 %
Oxygen	< 0.5 %	< 0.5 %
Boron Oxide	< 0.1 %	< 0.1 %
Carbon	< 0.1 %	< 0.1 %
Specific Surface Area (BET)	~ 1 m ² /g	~ 1 m ² /g
Median Grain Size (D₅₀)	~ 35 μm	45 μm

-  Particle size
-  Specific surface area
-  Degree of agglomeration
-  Crystallinity
-  Pourability
-  Bulk density
-  Particle size distribution



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